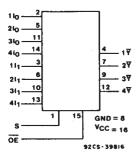
File Number 1775



High-Speed CMOS Logic





Quad 2-Input Multiplexer with 3-State Inverting Outputs

Type Features:

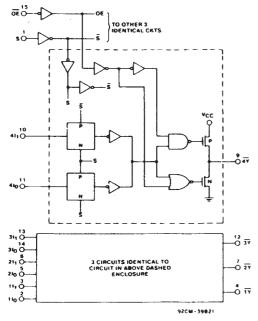
- Buffered inputs
- Typical CD54/74HC258 propagation delay = 7 ns @ Vcc = 5 V, CL = 15 pF, TA = 25°C

FUNCTIONAL DIAGRAM

The RCA-CD54/74HC258 and CD54/74HCT258 are guad 2input multiplexers which select four bits of data from two sources under the control of a common Select input (S). The Output Enable input (\overline{OE}) is active LOW. When \overline{OE} is HIGH, all of the outputs $(\overline{1Y}-\overline{4Y})$ are in the high impedance state regardless of all other input conditions.

Moying data from two groups of registers to four common output busses is a common use of the 258. The state of the Select input determines the particular register from which the data comes. It can also be used as a function generator.

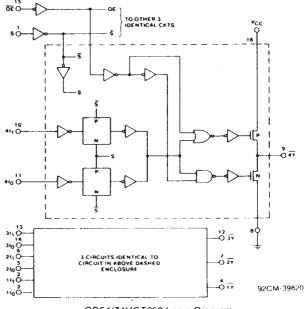
The CD54HC/HCT258 are supplied in 16-lead hermetic dual-in-line ceramic packages (F suffix). The CD74HC/ HCT258 are supplied in 16-lead dual-in-line plastic packages (E suffix) and in 16-lead dual-in-line surface mount plastic packages (M suffix). Both types are also available in chip form (H suffix).



CD54/74HC258 Logic Diagram

Family Features:

- Fanout (Over Temperature Range): Standard Outputs - 10 LSTTL Loads Bus Driver Outputs - 15 LSTTL Loads
- Wide Operating Temperature Range: CD74HC/HCT/HCU: -40 to +85°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- Alternate Source is Philips/Signetics
- CD54HC/CD74HC Types: 2 to 6 V Operation High Noise Immunity:
- NIL = 30%, NIH = 30% of VCC; @ VCC = 5V ■ CD54HCT/CD74HCT Types: 4.5 to 5.5 V Operation
 - Direct LSTTL Input Logic Compatibility $V_{\rm IL} = 0.8 \ V \ Max., \ V_{\rm IH} = 2 \ V \ Min.$ CMOS Input Compatibility 1, ≤ 1 μA @ Vol VoH



CD54/74HCT258 Logic Diagram

MAXIMUM RATINGS, Absolute-Maximum Values:

| DC SUPPLY-VOLTAGE, (Vcc): | |
|--|--------------------------------------|
| (Voltages referenced to ground) | 0.5 to + / V |
| DC INPUT DIODE CURRENT, IIK (FOR VI < -0.5 V OR VI > VCC +0.5V) | ±20mA |
| DC OUTPUT DIODE CURRENT, lox (FOR Vo < -0.5 V OR Vo > Vcc +0.5V) | ±20mA |
| DC DRAIN CURRENT PER OUTPUT (Ia) (FOR -0.5 V \leq V ₀ \leq V _{0c} + 0.5V) | ±35mA |
| DC V _{CC} OR GROUND CURRENT (I _{CC}) | ±70mA |
| POWER DISSIPATION PER PACKAGE (Pa): | |
| For T _A = -40 to +60°C (PACKAGE TYPE E) | 500 mW |
| For T ₂ = +60 to +85°C (PACKAGE TYPE E) | Derate Linearly at 8 mw/ C to 300 mw |
| For T _a = -55 to +100°C (PACKAGE TYPE F. H) | 500 mw |
| For T _* = +100 to +125°C (PACKAGE TYPE F, H) | Derate Linearly at 8 mW/°C to 300 mW |
| For T _A = -40 to +70°C (PACKAGE TYPE M) | 400 mw |
| For T _A = +70 to +125°C (PACKAGE TYPE M) | Derate Linearly at 6 mW/°C to 70 mW |
| OPERATING-TEMPERATURE BANGE (Ta): | |
| DAGMAGE TYPE E. H. | |
| PACKAGE TYPE E M | -40 to +85°C |
| STORAGE TEMPERATURE (Tstg) | 65 to +150°C |
| LEAD TEMPERATURE (DURING SOLDERING) | |
| At distance 1/16 \pm 1/32 in. (1.59 \pm 0.79 mm) from case for 10 s max | +265°C |
| Unit inserted into a PC Board (min. thickness 1/16 in., 1.59 mm) | . 其用 |
| Unit inserted into a PC Board (min. thickness 1/16 in., 1.59 mm) with solder contacting lead tips only | +300°C |
| With solder contacting lead tips only | |

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

| | LIN | UNITS | |
|---|------|-----------------|-------|
| CHARACTERISTIC | MIN. | MAX. | UNITS |
| Supply-Voltage Range (For T _A = Full Package-Temperature Range) V _{CC} :* | | | |
| CD54/74HC Types | 2 | 6 | V |
| CD54/74HCT Types | 4.5 | 5.5 | |
| DC Input or Output Voltage V _I , V _O | 0 | V _{cc} | |
| Operating Temperature T _A : | | | 1 |
| CD74 Types | -40 | +85 | l ∘c |
| CD54 Types | -55 | +125 | |
| Input Rise and Fall Times t _r , t _f | | | |
| at 2 V | 0 | 1000 | |
| at 4.5 V | 0 | 500 | ns |
| at 6 V | 0 | 400 | |

^{*}Unless otherwise specified, all voltages are referenced to Ground.

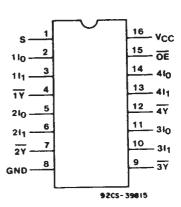
FUNCTION TABLE

| Output Enable | Select Input | 1 | ata outs | Output |
|------------------|-----------------|----------------|-------------|--------|
| ŌĒ | S | I ₀ | H | Ÿ |
| Н | Х | Х | Х | Z |
| L | L | L | Х | Н |
| L | L | Н | X | L |
| L | н | X | L | Н |
| L | н | X | Н | L |

H = High level voltage L = Low level voltage

X = Don't care.

Z = High impedance (off) state



TERMINAL ASSIGNMENT

1700

CD54/74HC258 CD54/74HCT258

STATIC ELECTRICAL CHARACTERISTICS

| | | CD74HC258/CD54HC258 | | | | | | | | CD74HCT258/CD54HCT258 | | | | | | | | | | |
|-------------------------------------|-----------------|---------------------|-----------------|------|---------------|------|------|-------------|------|-----------------------|---------------------------|-----------------|----------|----------|------------|---------------|--|-------------------|-------|-------|
| CHARACTERISTIC | co | TEST ONDITIONS | | | HC/54 TYPE | - | | HC PE | 1 | HC PE | TEST 74HCT/54HCT | | | | HCT (PE | 54HCT TYPE | | | | |
| | V, | I _o | V _{cc} | | +25°(| С | | 40/ 5° C | | 55/ 5°C | V, | V _{cc} | +25° | | : | : 1 | | 40/ -5 5°C +12 | | UNITS |
| Į. | | | ľ | Min | Тур | Max | Min | Max | Min | Max | | * | Min | Тур | Max | Min | Max | Min | Max | |
| High-Level | 1 | | 2 | 1.5 | - | - | 1.5 | - | 1.5 | _ | | 4.5 | - | - | | | | \vdash | | |
| Input Voltage V _{IH} | | 1 | 4.5 | 3.15 | - | | 3.15 | - | 3.15 | _ | _ | to | 2 | _ | _ | 2 | _ | 2 | _ | V |
| | | | 6 | 4.2 | - | - | 4.2 | _ | 4.2 | - | 1 | 5.5 | | | | | | | | |
| Low-Level | | | 2 | _ | _ | 0.5 | _ | 0.5 | - | 0.5 | | 4.5 | | | | | | 1 | T | |
| Input Voltage V _{IL} | | | 4.5 | _ | _ | 1.35 | - | 1.35 | _ | 1.35 | 1 _ | to | _ | _ | 0.8 | _ | 0.8 | _ | 0.8 | V |
| | | į | 6 | | _ | 1.8 | _ | 1.8 | _ | 1.8 | 1 | 5.5 | | 4 | | | | | | |
| High-Level | V _{IL} | | 2 | 1.9 | _ | _ | 1.9 | _ | 1.9 | _ | V _{IL} | 4, | 35 | 710 | | | | | | |
| Output Voltage V _{OH} | or | -0.02 | 4.5 | 4.4 | _ | _ | 4.4 | _ | 4.4 | _ | Or. | 4.5 | 4.4 | | (L) | 4.4 | _ | 4.4 | _ | V |
| CMOS Loads | Var | | 6 | 5.9 | _ | _ | 5.9 | _ | 5.9 | 3 | V _{IH} | 4 | 1 | | | | | | | |
| | V _K | | | | | | | | | | V _R | , | | | | | ļ | | | |
| TTL Loads | or | -6 | 4.5 | 3.98 | _ | _4 | 3.84 | _ | 3.7 | _ | or | 4.5 | 3.98 | _ | _ | 3.84 | _ | 3.7 | _ | v |
| (Bus Driver) | V _{iH} | -7.8 | 6 | 5.48 | 4 | _ | 5.34 | - | 5.2 | 2 | V _{IH} | · | | | | | | | | |
| Low-Level | V _{IL} | | 2 | | | 0.1 | | 0.1 | _ | 0.1 | V _{IL} | | | | | | | | | |
| Output Voltage Vol | or | 0.02 | 4.5 | | | 0.1 | _ | 0.1 | _ | 0.1 | or | 4.5 | _ | _ | 0.1 | _ | 0.1 | | 0.1 | v |
| CMOS Loads | V _{IH} | | 6 | 7 | _ | 0.1 | _ | 0.1 | | 0.1 | V _H | | | | | | | | | |
| | V _{IL} | | | | | | | | | | V _{IL} | | | | | | | | | |
| TTL Loads | or | 6 | 4.5 | _ | _ | 0.26 | | 0.33 | _ | 0.4 | or | 4.5 | _ | _ | 0.26 | | 0.33 | | 0.4 | v |
| (Bus Driver) | V _{IM} | 7.8 | 6 | _ | _ | 0.26 | _ | 0.33 | _ | 0.4 | V _{IH} | | | | | | | | | |
| Input Leakage | V _{cc} | | | | | | - | | | | Any | | \neg | \neg | | | | | | |
| Current I, | or | | 6 | _ | _ | ±0.1 | _ | ±1 | _ | ±1 | Voltage Between | 5.5 | _ | _ | ±0.1 | _ | ±1 | | ±1 | μΑ |
| | Gnd | | | | | | | | | | V _{cc} & Grid | | | | | | | | | - |
| Quiescent | V _{cc} | | | | | | | | | | V _{cc} | | | - | | | | | | |
| Device | or | 0 | 6 | _ | _ | 8 | _ | 80 | _ | 160 | or | 5.5 | _ | _ | 8 | _ | 80 | _ | 160 | μΑ |
| Current Icc | Gnd | | | | | | | | | | Gnd | | | | | | | | | |
| Additional | | 1 | 1 | 1 | | | | | 1 | \dashv | | 4.5 | \dashv | | | | \dashv | | | |
| Quiescent Device Current | | | | | | | | | | Ì | V _{cc} -2.1 | to | _ | 100 | 360 | _ | 450 | _ | 490 | μА |
| per input pin: 1 unit load Δlcc* | | | | | | | J | | 5.5 | | | | | | | | • | | | |
| 3-State | V _H | Vo = Vcc | | | | | П | | | | Vı | _ | \dashv | \dashv | - | | \neg | | _ | |
| leakage | or | or | 6 | _ | _ | ±0.5 | _ | ±5 | _ | ±10 | i | 5.5 | _ | _ | ±0.5 | _ | ±5 | _ | ±10 | μΑ |
| current loz | | | 1 | - 1 | ſ | - 1 | | | - 1 | | | | - 1 | - 1 | | Ì | | | - ' - | par 1 |

HCT Input Loading Table

| Input | Unit Loads* |
|-------|-------------|
| Data | 0.5 |
| S | 1.5 |
| ŌĒ | 1.5 |

^{*}Unit Load is ΔI_{CC} limit specified in Static Characteristic Chart, e.g., 360 μ A max. @ 25° C.

For dual-supply systems theoretical worst case (V_i = 2.4 V, V_{cc} = 5.5 V) specification is 1.8 mA.

SWITCHING CHARACTERISTICS (Vcc = 5 V, TA = 25°C, Input tr, tr = 6 ns)

| OHADAGTEDIGTIG | | CL | TYP | ICAL | UNITS |
|--|-----------------------------------|------|-----|------|-------|
| CHARACTERISTIC | | (pF) | НС | нст | DRITS |
| $nl_{o}, nl_{l}, to \overline{Y}_{v}$ | t _{PHL} t _{PLH} | 15 | 7 | 11 | ns |
| ŌĒ to Ÿ | t _{PZL} t _{PZH} | 15 | 11 | 11 | ns |
| | t _{PLZ} t _{PHZ} | 15 | 12 | 12 | ns |
| S to \overline{Y} | t _{PHL} t _{PLH} | 15 | 11 | 14 | ns |
| Power Dissipation Capacitance* | C _{PD} | _ | 49 | 49 | pF |

 $^{^*}C_{PD}$ is used to determine the dynamic power consumption, per multiplexer. $P_D = V_{CC}^2$ fi $(C_{PD} + C_L)$ where: fi = input frequency $C_L = c_L = c_L$ output load capacitance $c_L = c_L = c_L = c_L$

SWITCHING CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input t_r , $t_t = 6 \text{ ns}$)

| | | | 25°C | | | N 14 | 0°C | o +85° | C | -5 | | | | | |
|-------------------------------------|------------------|-----------------|------|------|------------|------|------|--------|----------|------|------|------|-------|------|-------|
| CHARACTERISTIC | | V _{cc} | HC | | HCT | | 74HC | | 74HCT | | 54HC | | 54HCT | | UNITS |
| | | | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. | |
| Propagation Delay, | t _{PLH} | 2 | | 95 | $\sqrt{-}$ | | 1 | 120 | _ | _ | _ | 145 | | _ | |
| nl_0 , nl_i , to \overline{Y} | t _{PHL} | 4.5 | | 19 | _ \ | 27 | | 24 | | 34 | - | 29 | — | 41 | ns |
| (Fig. 2) | | 6 | 9- | 15 | - | | | 20 | | | | 25 | | _ | |
| Propagation Delay | | 2 | | 140 | | - | l – | 175 | - | _ | — | 210 | | _ | |
| S to \overline{Y} | tpLH | 4.5 | + | 28 | _ | 34 | _ | 35 | _ | 43 | — | 42 | | 51 | ns |
| (Fig. 3) | t _{PHL} | 6 | _ | 24 | | | | 30 | | | | 36 | | _ | |
| Propagation Delay | | 2 | | 140 | - | _ | _ | 175 | _ | - | - | 210 | — | - | |
| OE to Y | tezL | 4.5 | _ | 28 | _ | 28 | _ | 35 | - | 35 | — | 42 | _ | 42 | ns |
| (Fig. 4) | tezh | 6 | - | 24 | _ | _ | | 30 | — | | | 36 | _ | | |
| Propagation Delay | tpLZ | 2 | _ | 150 | _ | _ | _ | 190 | _ | _ | - | 225 | _ | - | |
| OE to Y | | 4.5 | — | 30 | _ | 30 | _ | 38 | — | 38 | - | 45 | | 45 | ns |
| (Fig. 4) | tenz | 6 | _ | 26 | _ | _ | | 33 | | _ | _ | 38 | | | |
| Output Transition | t _{TLH} | 2 | _ | 60 | | _ | _ | 75 | _ | | _ | 90 | _ | _ | |
| Time | t _{THL} | 4.5 | - | 12 | | 12 | _ | 15 | — | 15 | _ | 18 | — | 18 | ns |
| (Fig. 2) | | 6 | | 10 | _ | ·— | | 13 | | | | 15 | | | |
| Input | | | | 10 | | 10 | | 10 | | 10 | | 10 | | 10 | pF |
| Capacitance | C, | | _ | 10 | _ | 10 | | 10 | | 10 | | 10 | | '0 | P1 |
| 3-State Output | | | | 20 | | 20 | | 20 | | 20 | | 20 | _ | 20 | рF |
| Capacitance | Co | | | 20 | _ | 20 | | 20 | <u> </u> | 20 | | 20 | | | Þ, |

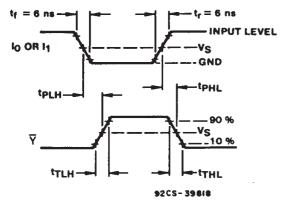


Fig. 2 - Select to output delays.

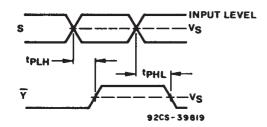


Fig. 3 - Select to output propagation delays.

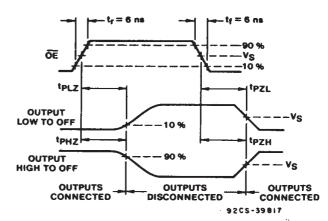


Fig. 4 - Output Enable to output propagation delays.

| 31 | 8- | |
|-----------------------|---------------------|----------|
| | 54/74HC | 54/74HCT |
| Input Level | V _{CC} | 3V |
| Switching Voltage, Vs | 50% V _{CC} | 1.3 V |

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